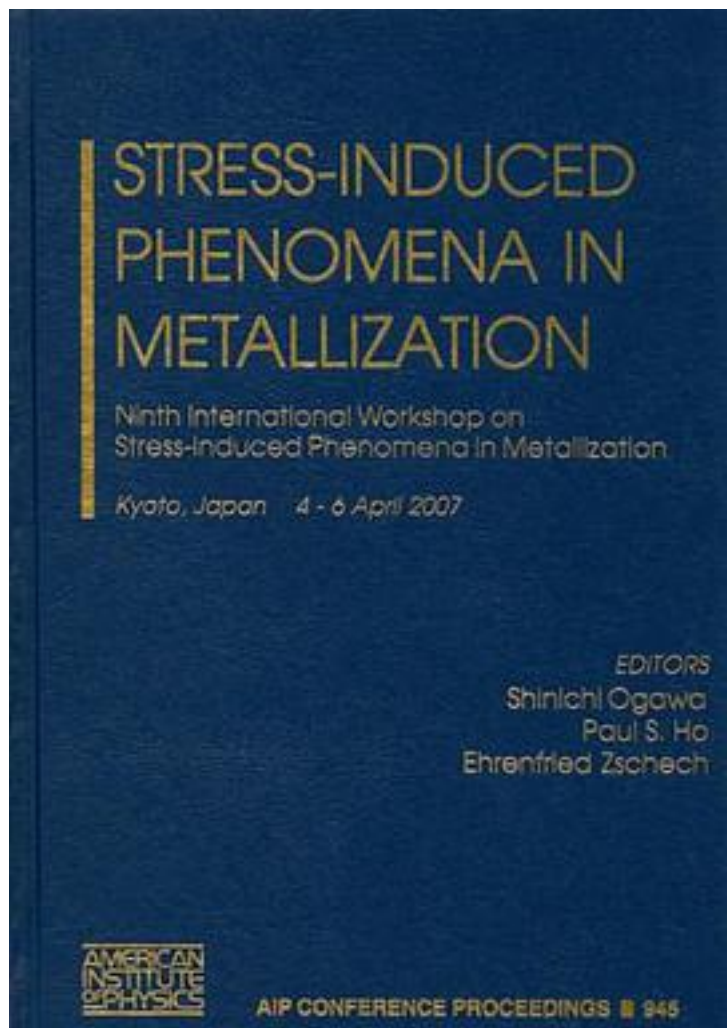


Stress-induced Phenomena in Metallization



[Stress-induced Phenomena in Metallization_下载链接1](#)

著者:Ogawa, Shinichi (EDT)/ Ho, Paul S. (EDT)/ Zschech, Ehrenfried (EDT)

出版者:

出版时间:2007-11

装帧:

isbn:9780735404595

The conference was on reliability related science in ULSI interconnect. Its main

purpose was to discuss the stress induced phenomena in the LSI interconnect among academic researchers and industry engineers to establish academic science and to improve the reliability of ULSI chips. All papers were peer reviewed.

作者介绍:

目录:

[Stress-induced Phenomena in Metallization_下载链接1](#)

标签

评论

[Stress-induced Phenomena in Metallization_下载链接1](#)

书评

[Stress-induced Phenomena in Metallization_下载链接1](#)